

ABSTRACT

A cooling unit includes a jacket configured to dissipate heat of the semiconductor device. The jacket includes a central portion and an outer portion. An opening through which light from the semiconductor device passes is formed in the central portion. The outer portion includes a contact portion that comes into contact with a stage on which the semiconductor device is disposed. A supply flow passage through which a cooling fluid for cooling the semiconductor device flows is formed in the jacket. A ventilation route configured to enable air circulation between an inner side of the outer portion and the outside of the jacket is formed in the jacket.

Fig. 8